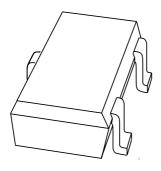
# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BAT854W series**Schottky barrier (double) diodes

Product data sheet 2001 Feb 27



# Schottky barrier (double) diodes

#### **BAT854W** series

#### **FEATURES**

- · Very low forward voltage
- · Very low reverse current
- · Guard ring protected
- · Very small SMD plastic package.

#### **APPLICATIONS**

- Ultra high-speed switching
- Voltage clamping
- · Protection circuits
- · Blocking diodes
- Low power consumption applications (e.g. hand-held applications).

#### **DESCRIPTION**

Planar Schottky barrier diodes encapsulated in a SOT323 very small SMD plastic package. Single diodes and double diodes with different pinning are available.

#### MARKING

TYPE NUMBER	MARKING CODE
BAT854W	81
BAT854AW	82
BAT854CW	83
BAT854SW	84

#### **PINNING**

PIN	SYMBOL				
BAT854W					
1	а				
2	n.c.				
3	k				
BAT854AW					
1	k <sub>1</sub>				
2	k <sub>2</sub>				
3	a <sub>1</sub> ,a <sub>2</sub>				
BAT854CW					
1	a <sub>1</sub>				
2	a <sub>2</sub>				
3	k <sub>1</sub> , k <sub>2</sub>				
BAT854SW					
1	a <sub>1</sub>				
2	k <sub>2</sub>				
3	k <sub>1</sub> , a <sub>2</sub>				

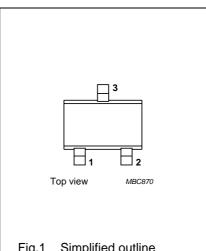


Fig.1 Simplified outline SOT323 and pin configuration.

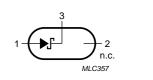


Fig.2 BAT854W single diode configuration (symbol).

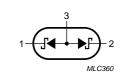


Fig.3 BAT854AW diode configuration (symbol).

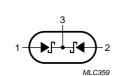


Fig.4 BAT854CW diode configuration (symbol).

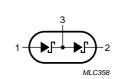


Fig.5 BAT854SW diode configuration (symbol).

# Schottky barrier (double) diodes

BAT854W series

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per diode					
V <sub>R</sub>	continuous reverse voltage		_	40	V
I <sub>F</sub>	continuous forward current		_	200	mA
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1 \text{ s}; \ \delta \le 0.5$	=	300	mA
I <sub>FSM</sub>	non-repetitive peak forward current	t = 8.3 ms half sinewave; JEDEC method	-	1	А
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
Per diode	1	<u> </u>			I
V <sub>F</sub>	continuous forward voltage	see Fig.6			
		$I_F = 0.1 \text{ mA}$	200	_	mV
		$I_F = 1 \text{ mA}$	260	_	mV
		I <sub>F</sub> = 10 mA	340	_	mV
		I <sub>F</sub> = 30 mA	_	420	mV
		I <sub>F</sub> = 100 mA	_	550	mV
I <sub>R</sub>	continuous reverse current	V <sub>R</sub> = 25 V; note 1; see Fig.7	_	0.5	μΑ
C <sub>d</sub>	diode capacitance	$V_R = 1 \text{ V; } f = 1 \text{ MHz; see Fig.8}$	_	20	pF

#### Note

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	625	K/W

#### Note

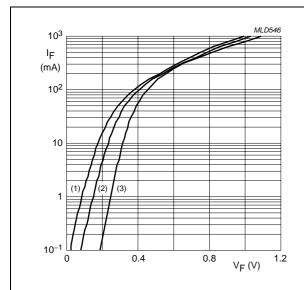
1. Refer to SOT323 standard mounting conditions.

<sup>1.</sup> Pulse test:  $t_p$  = 300  $\mu$ s;  $\delta$  = 0.02.

# Schottky barrier (double) diodes

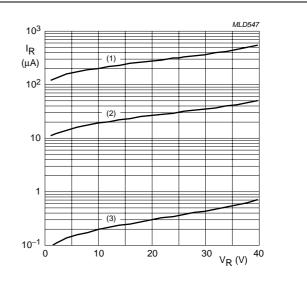
# BAT854W series

#### **GRAPHICAL DATA**



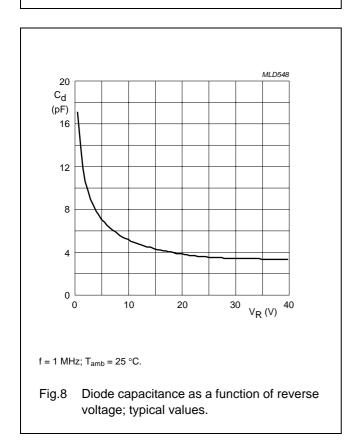
- (1)  $T_{amb} = 125 \, ^{\circ}C$ .
- (2)  $T_{amb} = 85 \, ^{\circ}C$ .
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.6 Forward current as a function of forward voltage; typical values.



- (1)  $T_{amb} = 125 \, ^{\circ}C$ .
- (2)  $T_{amb} = 85 \, ^{\circ}C$ .
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.7 Reverse current as a function of reverse voltage; typical values.



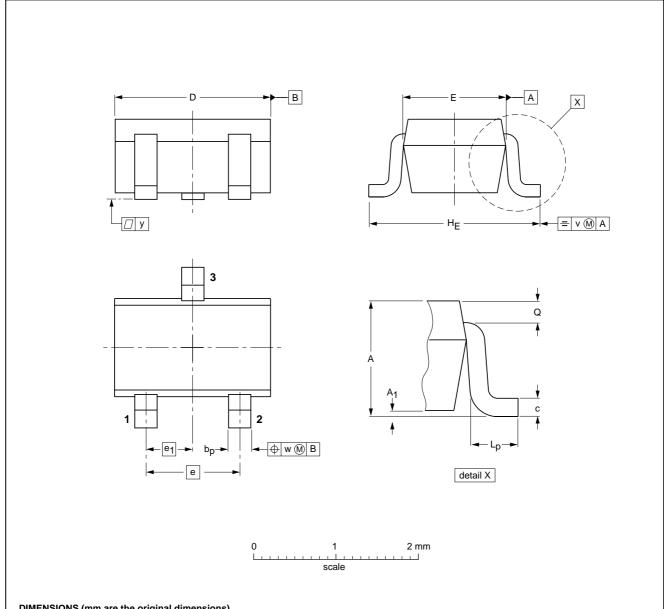
# Schottky barrier (double) diodes

# BAT854W series

#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

**SOT323** 



#### **DIMENSIONS** (mm are the original dimensions)

UNIT	Α	A <sub>1</sub> max	bp	ပ	D	E	е	e <sub>1</sub>	HE	Lp	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT323			SC-70			97-02-28

2001 Feb 27 5

# Schottky barrier (double) diodes

#### BAT854W series

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
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#### **Contact information**

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